

IN THE CLAIMS:

The following listing of claims will replace all prior versions and listings of claims in the subject application:

1. (Currently Amended) A liquid metal evaporation source for use in Molecular Beam Epitaxy (MBE) or vacuum deposition processes, said source comprising:
a high temperature an evaporator configured to evaporate liquid metal, said evaporator maintained at a first temperature;
an intermediate temperature hollow transport tube; and
a low temperature hollow reservoir cylinder with close mating having a cylindrical piston, said reservoir cylinder maintained at a third temperature that is lower than said first temperature;
a hollow transport tube maintained at a second temperature less than said first temperature and greater than said third temperature, said hollow transport tube connecting said evaporator and said reservoir cylinder;
at least one conducting probe configured to measure and regulate said liquid metal height within said evaporator; and
at least one heater element, each said heater element configured to maintain the temperature of one of at least said evaporator, said transport tube, and said reservoir cylinder to prevent solidification of liquid metal, each said heater element having a thermocouple configured to sense the temperature and control the temperature of said heating element;

~~wherein each of said evaporator, said transport tube and said reservoir cylinder include a radiant resistive heater element with a thermocouple to sense and regulate the heater power; and~~

wherein said reservoir cylinder and said piston are configured to prevent leakage of liquid metal through the mating surfaces of said reservoir cylinder and said piston;

wherein ~~said~~ at least one conducting probe is used ~~configured~~ to sense contact with liquid metal in said evaporator by making a low resistance electrical contact; and

wherein ~~said~~ conducting probe controls ~~in which the level of said conducting probe can be used to control~~ a position of said piston in said reservoir cylinder via an automatic feedback control circuit which drives a motor attached to a linear motion vacuum feedthrough which in turn is attached to said piston and is used to regulate a constant height ~~the level~~ of said liquid metal in said evaporator to maintain a constant evaporation rate of said liquid metal from said evaporator at a fixed evaporator temperature.

2. (Original) An evaporation source according to claim 1, wherein at least one of said evaporator, said hollow transport tube, said reservoir, and said piston are machined from a refractory material.

3. (Currently Amended) An evaporation source according to claim 2, wherein said refractory material is densified graphite having an efficient black-body radiation absorption that reduces the required heating element power required to achieve a selected operating temperature.

4. (Original) An evaporation source according to claim 2, wherein at least one of said evaporator, said reservoir cylinder, said transport tube and said piston are coated with a layer of Pyrolytic Graphite (PG).

5-7. (Cancelled)

8. (Currently Amended) An evaporation source according to claim 2, wherein two or more at least one of said evaporator, said hollow transport tube and said reservoir cylinder are [[is]] machined from a single piece of refractory material in essentially a concentric configuration with respect to each other.

9. (Original) An evaporation source according to claim 1, wherein said evaporator and said hollow transport tube are joined at a right angle to the axis of said reservoir cylinder by leak-tight flat flanges.

10. (Original) An evaporation source according to claim 9, wherein said reservoir cylinder is joined to said hollow transport tube and said evaporator via a passageway for said liquid metal.

11. (Original) An evaporation source according to claim 9, wherein said leak-tight flat flanges are attached using threaded assemblies.

12. (Original) An evaporation source according to claim 9, wherein said leak-tight flat flanges are attached using refractory clamps.

13. (Original) An evaporation source according to claim 1, wherein said evaporator and said hollow transport tube are joined at an angle ranging between 0 to 180 degrees to said reservoir cylinder along its axis by leak-tight flanges.

14. (Original) An evaporation source according to claim 13, wherein said reservoir cylinder is joined to said hollow transport tube and said evaporator via a passageway for said liquid metal.

15. (Original) An evaporation source according to claim 13, wherein said leak-tight flat flanges are attached using refractory clamps.

16. (Original) An evaporation source according to claim 13, wherein said leak-tight flat flanges are attached using threaded assemblies.

17. (Previously Presented) An evaporation source according to claim 15, wherein said refractory clamps are joined together using refractory nuts and bolts preferably made from molybdenum.

18. (Previously Presented) An evaporation source according to claim 15, wherein said refractory clamps are joined together using refractory nuts and bolts preferably made from densified graphite.

19. (Currently Amended) An evaporation source according to claim 155, wherein said opening in said nosecone is conically shaped to provide uniform dispersion of said evaporated metal and deliver uniform thickness deposition of said metal to coat a substrate.

20. (Cancelled)

21. (Original) An evaporation source according to claim 1, wherein at least one of said conducting probes are made from a non-reacting refractory material.

22. (Currently Amended) An evaporation source according to claim 21, wherein said refractory material is densified graphite having an efficient black-body radiation absorption that reduces the required heating element power required to achieve a selected operating temperature.

23. (Original) An evaporation source according to claim 22, wherein said conducting probes are insulated from each other and insulated from the walls of the evaporator.

24. (Original) An evaporation source according to claim 23, wherein said conducting probes are insulated from each other and insulated from the walls of the evaporator using non-conductive ceramic coating.

25. (Cancelled)

26. (Original) An evaporation source according to claim 24, wherein at least one of said conducting probes is positioned above the surface of said liquid metal.

27. (Original) An evaporation source according to claim 24, wherein at least one of said conducting probes is inserted from below the surface of said liquid metal through said evaporator.

28. (Original) An evaporation source according to claim 21, wherein at least one of said conducting probes makes a first contact with said liquid metal on its surface and makes a second contact with said liquid metal through conductive walls of said evaporator.

29. (Currently Amended) An evaporation source according to claim 1, wherein said ~~radiant resistive~~ heater elements are made from refractory materials.

30. (Currently Amended) An evaporation source according to claim 29, wherein said refractory material is densified graphite having an efficient black-body radiation

absorption that reduces the required heating element power required to achieve a selected operating temperature.

31. (Currently Amended) An evaporation source according to claim 30, wherein said ~~radiant resistive~~ heater elements are configured in a serpentine or spiral fashion.

32-39. (Cancelled)

40. (Original) An evaporation source according to claim 1, wherein the position of said piston in said reservoir is manually set.

41. (Original) An evaporation source according to claim 40, wherein said position is set using a micrometer screw attached to said linear motion vacuum feedthrough attached to a shaft driving said piston.

42. (Original) An evaporation source according to claim 41, wherein the position is set using a motor to drive said micrometer screw.

43. (Original) An evaporation source according to claim 1, wherein the position of said piston in said reservoir is automatically adjusted.

44. (Original) An evaporation source according to claim 43, wherein the position of said piston is automatically adjusted using an electronic feedback control circuit.

45. (Previously Presented) An evaporation source according to claim 44, wherein said electronic feedback control circuit senses the electrical contact resistance between said liquid metal and said at least one conducting probe.

46. (Original) An evaporation source according to claim 45, wherein said electronic feedback control circuit applies power to a motor that drives a micrometer screw attached to said linear motion vacuum feedthrough attached to a shaft driving said piston.

47. (Original) An evaporation source according to claim 1, wherein said refractory material for said source is chosen not to react with said liquid metal at temperatures required to achieve evaporation of said liquid metal.

48. (Original) An evaporation source according to claim 1, wherein said liquid metal is selected from the group consisting of Silver (Ag), Aluminum (Al), Gold (Au), Boron (B), Barium (Ba), Bismuth (Bi), Cadmium (Cd), Cobalt (Co), Cesium (Cs), Copper (Cu), Iron (Fe), Gallium (Ga), Gadolinium (Gd), Germanium (Ge), Mercury (Hg), Indium (In), Potassium (K), Lanthanum (La), Lithium (Li), Sodium (Na), Nickel (Ni), Lead (Pb), Palladium (Pd), Praseodymium (Pr), Platinum (Pt), Rubidium (Rb), Antimony (Sb), Scandium (Sc), Selenium (Se), Silicon (Si), Tin (Sn), Tellurium (Te), Thallium (Tl), Vanadium (V), Ytterbium (Y), and Zinc (Zn).

49. (Currently Amended) A liquid metal evaporation source for use in Molecular Beam Epitaxy (MBE) or vacuum deposition processes, said evaporation source comprising:

 a first zone maintained at a first temperature;

 a second zone maintained at a second temperature lower than said first temperature; and

 a third zone maintained at a third temperature lower than said second temperature;

 wherein each of said first, second and third zones include a heater means for element for sensing and regulating said first, second and third temperatures of said first, second and third zones to prevent solidification of liquid metal; and

 wherein said first, second and third zones are in fluid communication.

50. (Currently Amended) An evaporation source according to claim 49, wherein said first zone includes an evaporator, said second zone includes a hollow transport tube, and said third zone includes a reservoir with a ~~close mating~~ piston.

51. (Previously Presented) An evaporation source according to claim 50, wherein at least one of said evaporator, said hollow transport tube and said reservoir is made from refractory material.

52. (Currently Amended) An evaporation source according to claim 51, wherein heater element regulates said first, second and third temperatures by infrared radiation and wherein said refractory material is densified graphite having an efficient black-body

radiation absorption that reduces the required heating element power required to achieve a selected operating temperature.

53. (Original) An evaporation source according to claim 52, wherein said refractory material does not react with said liquid metal at temperatures required for evaporation of said liquid metal.

54. (Original) An evaporation source according to claim 51, wherein at least one of said evaporator, said hollow transport tube and said reservoir is coated with a layer of material selected from the group consisting of Pyrolytic Graphite (PG), Pyrolytic Boron Nitride (PBN), Pyrolytic Silicon Carbide (PSiC), and Pyrolytic Aluminum Nitride (PAN).

55. (Previously Presented) An evaporation source according to claim 50, wherein said evaporation source includes at least one conducting probe used to sense contact with liquid metal in said evaporator.

56. (Original) An evaporation source according to claim 55, wherein at least one of said conducting probes is made from a non-reacting refractory material.

57. (Currently Amended) An evaporation source according to claim 56, wherein said non-reacting refractory material is densified graphite having an efficient black-body

radiation absorption that reduces the required heating element power required to achieve a selected operating temperature.

58. (Original) An evaporation source according to claim 57, wherein said conducting probes are insulated from each other and insulated from the walls of said evaporator.

59. (Original) An evaporation source according to claim 58, wherein ceramic coating is said insulator.

60-62. (Cancelled)

63. (Original) An evaporation source according to claim 55, wherein at least one of said conducting probes makes a first contact with said liquid metal on its surface and makes a second contact with said liquid metal through conductive walls of said evaporator.

64. (Previously Presented) An evaporation source according to claim 63, wherein said at least one conducting probe controls the position of said piston via an automatic feedback control circuit.

65. (Previously Presented) An evaporation source according to claim 64, wherein said automatic feedback control circuit drives a motor attached to said piston and

regulates a constant height of said liquid metal in said evaporator.

66. (Currently Amended) An evaporation source according to claim 50, wherein two or more at least one of said evaporator, said hollow transport tube, and said reservoir are machined from a single piece of refractory material in essentially a concentric configuration with respect to each other.

67. (Original) An evaporation source according to claim 50, wherein said evaporator and said hollow transport tube are joined at a right angle to the axis of said reservoir by leak-tight flat flanges.

68. (Original) An evaporation source according to claim 67, wherein said evaporation source includes a co-joining passageway for said liquid metal between said reservoir and said hollow transport tube.

69. (Original) An evaporation source according to claim 67, wherein said leak-tight flat flanges are attached using threaded assemblies.

70. (Original) An evaporation source according to claim 67, wherein said leak-tight flat flanges are attached using refractory clamps.

71. (Original) An evaporation source according to claim 70, wherein said refractory clamps are joined using refractory nuts and bolts.

72. (Original) An evaporation source according to claim 50, wherein said evaporator and said hollow transport tube are joined at an angle in the range of 0 to 180 degrees to said reservoir along its axis by leak-tight flanges.

73. (Original) An evaporation source according to claim 72, wherein said evaporation source includes a co-joining passageway for said liquid metal between said reservoir and said hollow transport tube.

74. (Original) An evaporation source according to claim 72, wherein said leak-tight flat flanges are attached using threaded assemblies.

75. (Original) An evaporation source according to claim 72, wherein said leak-tight flat flanges are attached using refractory clamps.

76. (Original) An evaporation source according to claim 75, wherein said refractory clamps are joined together using refractory nuts and bolts.

77. (Currently Amended) An evaporation source according to claim 50, wherein said evaporator includes an evaporator nosecone having at least one said conducting probe disposed therein.

78. (Currently Amended) An evaporation source according to claim 77, wherein said evaporator nosecone ~~is configured to a shape suitable for providing a metal beam flux profile incident upon a substrate~~ comprises a conically shaped opening configured to provide uniform dispersion of said evaporated metal and deliver a uniform deposition of said metal on a substrate.

79-80. (Cancelled)

81. (Currently Amended) An evaporation source according to claim 49, wherein at least one of said heater means elements is made from refractory materials.

82. (Currently Amended) An evaporation source according to claim 81, wherein at least one of said heater means elements is configured in a serpentine or spiral fashion.

83. (Currently Amended) An evaporation source according to claim 49, wherein at least one of said heater means elements is densified graphite having an efficient black-body radiation absorption that reduces the required heating element power required to achieve a selected operating temperature.

84-91. (Cancelled)

92. (Original) An evaporation source according to claim 50, wherein the position of said piston in said reservoir is manually set.

93. (Previously Presented) An evaporation source according to claim 92, wherein said position is set using a micrometer screw attached to a linear motion vacuum feedthrough attached to a shaft driving said piston.

94. (Original) An evaporation source according to claim 93, wherein the position is set using a motor to drive said micrometer screw.

95. (Original) An evaporation source according to claim 50, wherein the position of said piston in said reservoir is automatically adjusted.

96. (Original) An evaporation source according to claim 95, wherein the position of said piston is automatically adjusted using an electronic feedback control circuit.

97. (Original) An evaporation source according to claim 96, wherein said electronic feedback control circuit senses the electrical contact resistance between said liquid metal and said conducting probes.

98. (Original) An evaporation source according to claim 97, wherein said electronic feedback control circuit applies power to a motor that drives a micrometer screw attached to said linear motion vacuum feedthrough attached to a shaft driving said piston.

99. (Original) An evaporation source according to claim 51, wherein said refractory material for said source is chosen not to react with said liquid metal at temperatures required to achieve evaporation of said liquid metal.

100. (Original) An evaporation source according to claim 49, wherein said liquid metal is selected from the group consisting of Silver (Ag), Aluminum (Al), Gold (Au), Boron (B), Barium (Ba), Bismuth (Bi), Cadmium (Cd), Cobalt (Co), Cesium (Cs), Copper (Cu), Iron (Fe), Gallium (Ga), Gadolinium (Gd), Germanium (Ge), Mercury (Hg), Indium (In), Potassium (K), Lanthanum (La), Lithium (Li), Sodium (Na), Nickel (Ni), Lead (Pb), Palladium (Pd), Praseodymium (Pr), Platinum (Pt), Rubidium (Rb), Antimony (Sb), Scandium (Sc), Selenium (Se), Silicon (Si), Tin (Sn), Tellurium (Te), Thallium (Tl), Vanadium (V), Ytterbium (Y), and Zinc (Zn).

101. (Currently Amended) A liquid metal evaporation source for use in Molecular Beam Epitaxy (MBE) or vacuum deposition processes, said evaporation source comprising:

- an evaporator;
- a transport tube; and
- a reservoir with ~~close-mating~~ piston;

a nosecone disposed at said evaporator; and
at least two conducting probes, a first conducting probe disposed at said
evaporator and a second conducting probe disposed at said nosecone;
wherein said first probe is in thermal communication with said evaporator and
said second probe is in thermal communication with said nosecone to maintain said first
and second probes at temperatures to prevent condensation of evaporated metal;

wherein each of said evaporator, said transport tube and said reservoir include a heater element having a thermocouple for sensing and regulating the temperature, ~~and~~;
wherein said heater elements heat said evaporator, said transport tube and said
reservoir by infrared radiation to prevent solidification of liquid metal in said evaporator,
said transport tube and said reservoir; and

wherein said evaporator, said transport tube and said reservoir are in fluid communication.

102. (Previously Presented) An evaporation source according to claim 101,
wherein said evaporator is maintained at a high temperature.

103. (Previously Presented) An evaporation source according to claim 101,
wherein said transport tube is maintained at a temperature lower than said evaporator.

104. (Previously Presented) An evaporation source according to claim 101,
wherein said reservoir is maintained at a lower temperature than said transport tube.

105. (Previously Presented) An evaporation source according to claim 101, wherein at least one of said evaporator, said transport tube and said reservoir is made from refractory material.

106. (Currently Amended) An evaporation source according to claim 105, wherein said refractory material is densified graphite having an efficient black-body radiation absorption that reduces the required heating element power required to achieve a selected operating temperature.

107. (Original) An evaporation source according to claim 105, wherein said refractory material does not react with said liquid metal at temperatures required for evaporation of said liquid metal.

108. (Original) An evaporation source according to claim 101, wherein at least one of said evaporator, said transport tube and said reservoir is coated with a layer of material selected from the group consisting of Pyrolytic Graphite (PG), Pyrolytic Boron Nitride (PBN), Pyrolytic Silicon Carbide (PSiC), and Pyrolytic Aluminum Nitride (PAN).

109. (Currently Amended) An evaporation source according to claim 101, wherein said evaporation source includes at least one conducting probes are used to sense contact with liquid metal in said evaporator.

110. (Original) An evaporation source according to claim 109, wherein at least one of said conducting probes is made from a non-reacting refractory material.

111. (Currently Amended) An evaporation source according to claim 110, wherein said non-reacting refractory material is densified graphite having an efficient black-body radiation absorption that reduces the required heating element power required to achieve a selected operating temperature.

112. (Original) An evaporation source according to claim 111, wherein said conducting probes are insulated from each other and insulated from the walls of said evaporator.

113. (Original) An evaporation source according to claim 112, wherein ceramic coating is said insulator.

114. (Cancelled)

115. (Original) An evaporation source according to claim 109, wherein at least one of said conducting probes is positioned above the surface of said liquid metal.

116. (Original) An evaporation source according to claim 109, wherein at least one of said conducting probes is inserted from below the surface of said liquid metal through said evaporator.

117. (Original) An evaporation source according to claim 109, wherein at least one of said conducting probes makes a first contact with said liquid metal on its surface and makes a second contact with said liquid metal through conductive walls of said evaporator.

118. (Previously Presented) An evaporation source according to claim 109, wherein said at least one conducting probe controls the position of said piston via an automatic feedback control circuit.

119. (Previously Presented) An evaporation source according to claim 118, wherein said automatic feedback control circuit drives a motor attached to said piston and regulates a constant height of said liquid metal in said evaporator.

120. (Currently Amended) An evaporation source according to claim 101, wherein two or more at least one of said evaporator, said transport tube, and said reservoir are machined from a single piece of refractory material in essentially a concentric configuration with respect to each other.

121. (Original) An evaporation source according to claim 101, wherein said evaporator and said transport tube are joined at a right angle to the axis of said reservoir by leak-tight flat flanges.

122. (Original) An evaporation source according to claim 121, wherein said evaporation source includes a co-joining passageway for said liquid metal between said reservoir and said transport tube.

123. (Original) An evaporation source according to claim 121, wherein said leak-tight flat flanges are attached using threaded assemblies.

124. (Original) An evaporation source according to claim 121, wherein said leak-tight flat flanges are attached using refractory clamps.

125. (Original) An evaporation source according to claim 124, wherein said refractory clamps are joined using refractory nuts and bolts.

126. (Original) An evaporation source according to claim 101, wherein said evaporator and said transport tube are joined at an angle in the range of 0 to 180 degrees to said reservoir along its axis by leak-tight flanges.

127. (Original) An evaporation source according to claim 126, wherein said evaporation source includes a co-joining passageway for said liquid metal between said reservoir and said transport tube.

128. (Original) An evaporation source according to claim 126, wherein said leak-tight flat flanges are attached using threaded assemblies.

129. (Original) An evaporation source according to claim 126, wherein said leak-tight flat flanges are attached using refractory clamps.

130. (Original) An evaporation source according to claim 129, wherein said refractory clamps are joined together using refractory nuts and bolts.

131. (Currently Amended) An evaporation source according to claim 101, wherein said ~~evaporator includes an evaporator nosecone~~ comprises a conically shaped opening configured to provide uniform dispersion of said evaporated metal and deliver a uniform disposition of said metal on a substrate.

132. (Cancelled)

133. (Currently Amended) An evaporation source according to claim 101, wherein said heater means element is made from refractory materials.

134. (Currently Amended) An evaporation source according to claim 133, wherein said heater means element is densified graphite having an efficient black-body radiation absorption that reduces the required heating element power required to achieve a selected operating temperature.

135. (Currently Amended) An evaporation source according to claim 134, wherein said heater ~~means~~ element is configured in a serpentine or spiral fashion.

136-143. (Cancelled)

144. (Original) An evaporation source according to claim 101, wherein the position of said piston in said reservoir is manually set.

145. (Previously Presented) An evaporation source according to claim 144, wherein said position is set using a micrometer screw attached to a linear motion vacuum feedthrough attached to a shaft driving said piston.

146. (Original) An evaporation source according to claim 145, wherein the position is set using a motor to drive said micrometer screw.

147. (Original) An evaporation source according to claim 101, wherein the position of said piston in said reservoir is automatically adjusted.

148. (Original) An evaporation source according to claim 147, wherein the position of said piston is automatically adjusted using an electronic feedback control circuit.

149. (Previously Presented) An evaporation source according to claim 148,

wherein said electronic feedback control circuit senses the electrical contact resistance between said liquid metal and at least one conducting probe.

150. (Original) An evaporation source according to claim 149, wherein said electronic feedback control circuit applies power to a motor that drives a micrometer screw attached to said linear motion vacuum feedthrough attached to a shaft driving said piston.

151. (Original) An evaporation source according to claim 101, wherein said refractory material for said source is chosen not to react with said liquid metal at temperatures required to achieve evaporation of said liquid metal.

152. (Original) An evaporation source according to claim 101, wherein said liquid metal is selected from the group consisting of Silver (Ag), Aluminum (Al), Gold (Au), Boron (B), Barium (Ba), Bismuth (Bi), Cadmium (Cd), Cobalt (Co), Cesium (Cs), Copper (Cu), Iron (Fe), Gallium (Ga), Gadolinium (Gd), Germanium (Ge), Mercury (Hg), Indium (In), Potassium (K), Lanthanum (La), Lithium (Li), Sodium (Na), Nickel (Ni), Lead (Pb), Palladium (Pd), Praseodymium (Pr), Platinum (Pt), Rubidium (Rb), Antimony (Sb), Scandium (Sc), Selenium (Se), Silicon (Si), Tin (Sn), Tellurium (Te), Thallium (Tl), Vanadium (V), Ytterbium (Y), and Zinc (Zn).

153. (New) An evaporator source according to claim 1, wherein a maximum permissible gap between said reservoir cylinder inner diameter and said piston cylinder

outer diameter is configured to contain the liquid metal within said reservoir by the surface tension of the liquid metal and is calculated by the formula:

$$\Delta = \frac{2\gamma}{[\rho gh]},$$

wherein Δ is the maximum permissible gap;

wherein γ is the liquid metal surface tension;

wherein ρ is the density of the liquid metal;

wherein g is the gravitational constant; and

wherein h is the vertical height difference between the liquid metal in the evaporator above the piston surface.

154. (New) An evaporator source according to claim 101, wherein a maximum permissible gap between said reservoir cylinder inner diameter and said piston cylinder outer diameter is configured to contain the liquid metal within said reservoir by the surface tension of the liquid metal and is calculated by the formula:

$$\Delta = \frac{2\gamma}{[\rho gh]},$$

wherein Δ is the maximum permissible gap;

wherein γ is the liquid metal surface tension;

wherein ρ is the density of the liquid metal;

wherein g is the gravitational constant; and

wherein h is the vertical height difference between the liquid metal in the evaporator above the piston surface.

155. (New) An evaporator source according to claim 1, wherein a nosecone is disposed at said evaporator to permit said evaporated metal to escape through an opening in said nosecone, at least one said conducting probe disposed therein.